

L Number	Hits	Search Text	DB	Time stamp
-	656	(257/697).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:33
-	137	((257/697).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:38
-	779	(257/696).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:33
-	52	((257/696).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:38
-	5	("3911475" "4001655" "4717948" "4758875" "4803543").PN.	USPAT	2002/03/16 11:36
-	6	5130780.URPN.	USPAT	2002/03/16 11:37
-	1057	(257/693).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:38
-	146	((257/693).CCLS.) and ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 11:38
-	15	("4965653" "5218234" "5291062" "5334857" "5355283" "5433822" "5468999" "5497032" "5552635" "5581122" "5598036" "5604379" "5640047" "5717252" "5731630").PN.	USPAT	2002/03/16 11:40
-	3	("5350947" "5352926" "5367435").PN.	USPAT	2002/03/16 11:40
-	5	5731630.URPN.	USPAT	2002/03/16 11:48
-	5	5731630.URPN.	USPAT	2002/03/16 14:26
-	2973	tape with lead with frame	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 14:32
-	21	tape with lead with frame with ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 14:56
-	828	tape with ceramic with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:03
-	121	(tape with ceramic with substrate) and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:07
-	50	glass adj epoxy with ceramic and tape and lead and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:11

-	15	glass adj epoxy with ceramic with heat and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:13
-	34743	chip with wire better with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:14
-	34657	chip with wire better with solder with cost and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:15
-	0	chip with wire with better with solder with cost and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:16
-	0	chip with wire with better with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:16
-	597	chip with wire with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:16
-	7	chip with wire with solder with design and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:21
-	8	(wire with bond with solder with design and (257/\$).ccls.) not ((257/693).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:19
-	5	(wire with bond with solder with design and (257/\$).ccls.) not (chip with wire with solder with design and (257/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:19
-	8	wire with bond with solder with design and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:20
-	13	Solder with wire with bumping and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:24
-	4	Solder with wire with integration and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:29
-	2	6339260.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 15:26
-	32	wire with cost with solder and (257/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/03/16 16:36

-	2	6064116.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/03/16 16:36
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